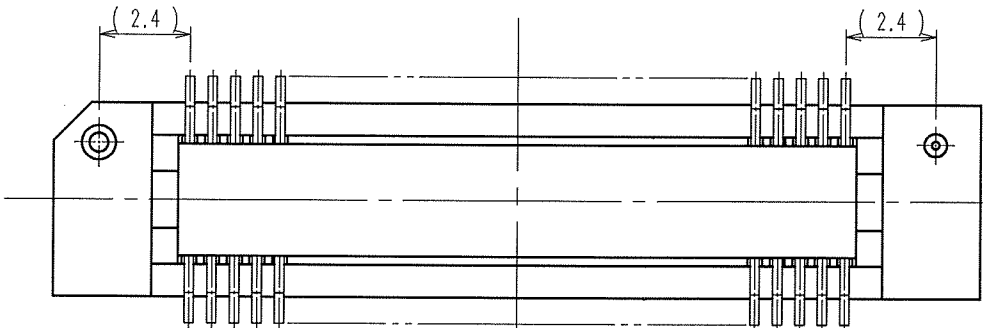
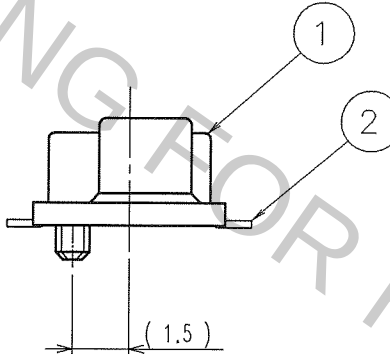
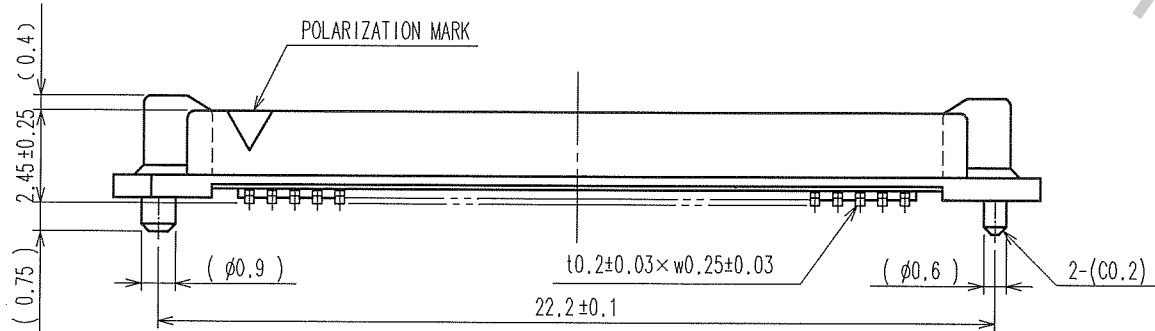
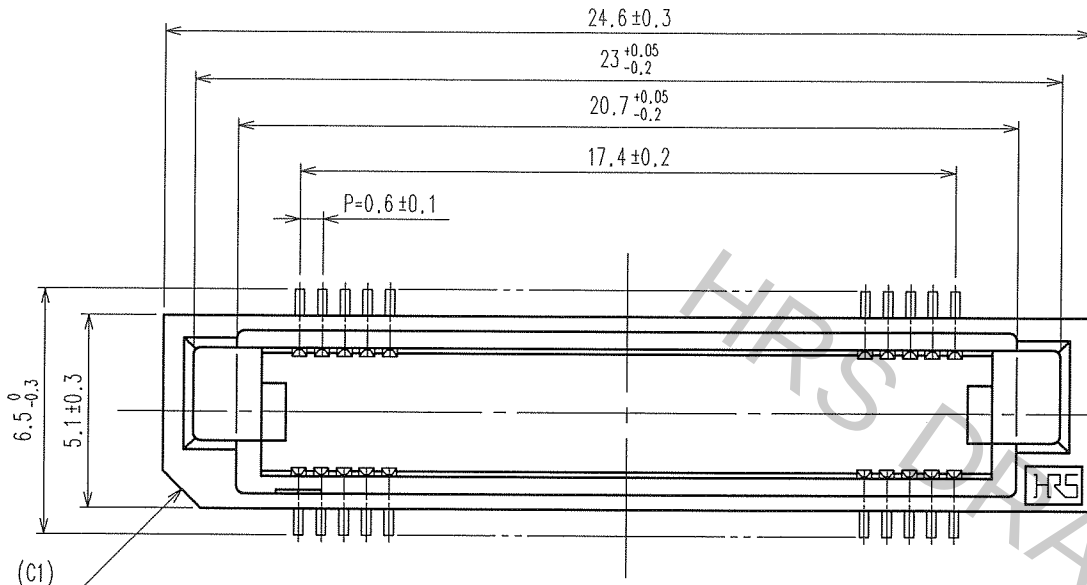
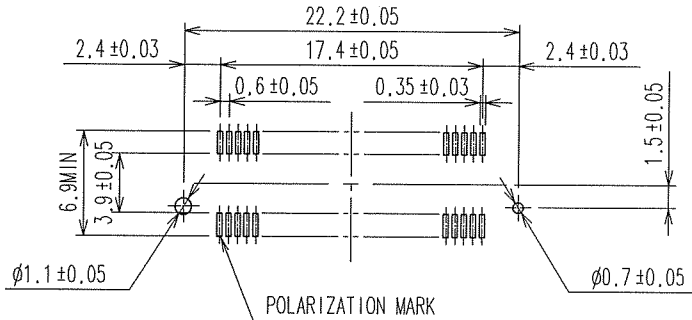


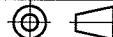
COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△				. .	△				. .
△				. .	△				. .
△				. .	△				. .



RECOMMENDED LAND PATTERN DIMENSION OF PCB
(MOUNTING SIDE) (2:1)



- NOTE 1. LEAD CO-PLANARITY SHALL BE 0.1mm.
2. FOR MODIFICATION ,ETC., PREVENTIVE HOLE FOR SINK MARK MAY BE ADDED ACCORDING TO CIRCUMSTANCES.
3. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

1	Polyphenylene Sulfide	LIGHT BROWN	UL94V-0	2	PHOSPHOR BRONZE	CONTACT AREA: GOLD 0.1μ m min.							
						MOUNTING AREA: GOLD PLATING FLASH							
						UNDER PLATING : NICKEL 0.5μ m min.							
NO.		MATERIAL		FINISH, REMARKS		NO.		MATERIAL		FINISH, REMARKS			
CODE NO. (OLD) CL				DRAWN T. NODA '05.06.27		DESIGNED H. Sai '05.06.29		CHECKED H. Ogawa '05.06.30		APPROVED H. Okawa '05.06.30		RELEASED . .	
		DRAWING NO.				PART NO.							
		EDC3-150564-25				FX8-60P-SV(71)							
		UNITS mm				CODE NO. CL578-0001-6-71							
 HIROSE ELECTRIC CO., LTD				1/1									